

Title (en)
SOLDER COATING MATERIAL AND PRODUCTION METHOD THEREFOR

Title (de)
MATERIAL FÜR LOTBESCHICHTUNG UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
MATERIAU DE REVETEMENT A BRASURE ET PROCEDE DE PRODUCTION CORRESPONDANT

Publication
EP 1211011 A4 20070502 (EN)

Application
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Priority
JP 9905777 W 19991020

Abstract (en)
[origin: EP1211011A1] The present invention is a solder coated material having a large amount of solder adhered to a difficult to solder material such as Kovar or Alloy 42 and a method which can adhere a sufficient amount of solder to a difficult to solder material without using flux. An electroplated coating is applied to a portion to be soldered of a difficult to solder material, the difficult to solder material is then passed through molten solder to which ultrasonic waves are applied, and a large amount of solder is adhered only to solder plated portions.

IPC 8 full level
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